

IN THE SPECIFICATION

Please replace the following paragraphs:

Page 3 through 4, paragraph [0007].

[0007] According to one embodiment, a processor loading apparatus is provided that can apply the high amount of force necessary to mate a processor to a processor socket without subjecting the processor socket solder joints to unwanted stresses. To this end, a processor loading apparatus includes a board member, a frame member mounted to the board member, a plurality of connector members on the frame member, and a resilient load member. The resilient load member has a first end ~~moveably~~ connected to one of the connector portions and a second end ~~forcibly~~ connected to another one of the connector portions. A processor socket is mounted to the board member and a processor is seated in the processor socket. ~~Forcible~~ The connection of the second end to the connector portion deforms the load member into engagement with the processor and urges the processor into the processor socket.

Page 5, paragraph [0017].

[0017] Fig. 11 is a perspective view illustrating an embodiment of a heat sink mounted to a frame member.

Page 5, paragraph [0018].

[0018] Fig. 12 is a cross-sectional view illustrating an embodiment of a resilient load member in a retaining position with a heat sink mounted to a frame member.

Page 8, paragraph [0027].

**[0027]**      A-The heat sink 80, FIG. 10 and 11, can then be mounted on frame member 26. Processor socket 104 and frame member 26 are mounted on board 100, with processor 12 seated in socket 104 and resilient load member 50 connected to frame member 26. A support member 120 is mounted on an opposite side of board 100 from frame 26 to support the weight of heat sink 80 on board 100. Heat sink 80 is mounted in frame member 26, FIG. 5, 9, 11, and 12, by engaging heat sink base 82 with heat sink engagement surface 32. Connection end 84 is placed on surface 32 and beneath heat sink retention members 34a and 34b. Connection end 86 may then be used to secured heat sink 80 to frame member 26 by placing it on surface 32 and below heat sink retention member 34c. When heat sink 80 is secured to frame 26, heat sink 80 engages thermal connection surface 112 on processor 12 and is positioned above load member surface 64.